


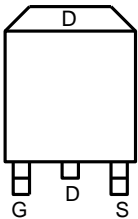
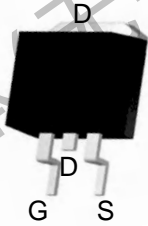
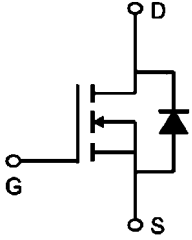


# TMG120N20T

# N-Channel Enhancement Mosfet

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 200V</math> <math>I_D = 120A</math></p> <p><math>R_{DS(ON)} = 8.8 m\Omega (typ.) @ V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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T:TO-263-3L

Marking: G120N20

**Absolute Maximum Ratings** ( $T_C = 25^\circ C$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	200	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	120	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	81	A
$I_{DM}$	Pulsed Drain Current	460	A
EAS	Single Pulse Avalanche Energy	324	mJ
$I_{AS}$	Avalanche Current	36	A
$P_D$	Total Power Dissipation	357	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	45	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	0.42	$^\circ C/W$



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Electrical Characteristics: ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	200	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=60A$	---	8.8	10.6	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	2.5	3	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=200V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=200V, V_{GS}=0V, T_J=100^\circ\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=60A$	---	103.5	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	3.5	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=100V, V_{GS}=10V, I_D=60A$	---	74	---	nC
$Q_{gs}$	Gate-Source Charge		---	30	---	
$Q_{gd}$	Gate-Drain Charge		---	16	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DD}=100V, R_G=2.7\Omega, I_D=60A$	---	35	---	ns
$T_r$	Rise Time		---	111	---	
$T_{d(off)}$	Turn-Off Delay Time		---	84	---	
$T_f$	Fall Time		---	112	---	
$C_{iss}$	Input Capacitance	$V_{DS}=100V, V_{GS}=0V, f=1\text{MHz}$	---	5268	---	$\mu F$
$C_{oss}$	Output Capacitance		---	462	---	
$C_{rss}$	Reverse Transfer Capacitance		---	24	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	120	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=60A, T_J=25^\circ\text{C}$	---	---	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_F=17A, di/dt=100A/\mu s$ ,	---	150.8	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	779.4	---	nC



**TMG120N20T**

**N-Channel Enhancement Mosfet**

**Typical Performance Characteristics**

Fig 1: Output Characteristics

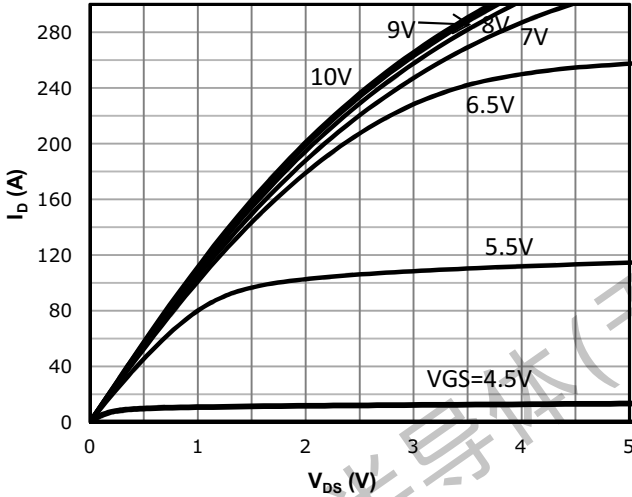


Fig 2: Transfer Characteristics

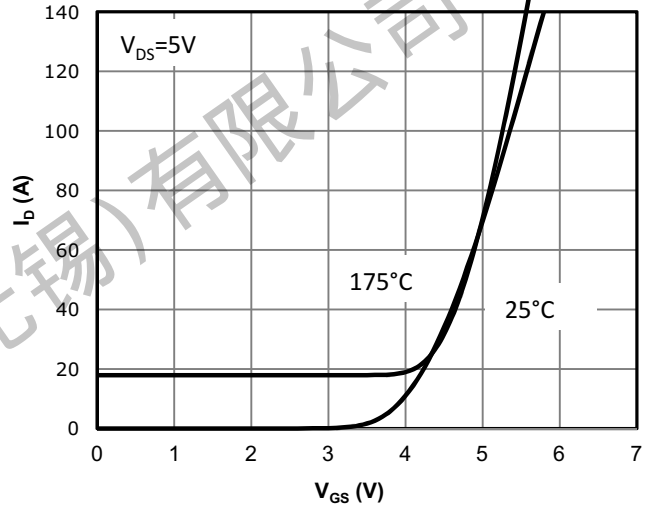


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

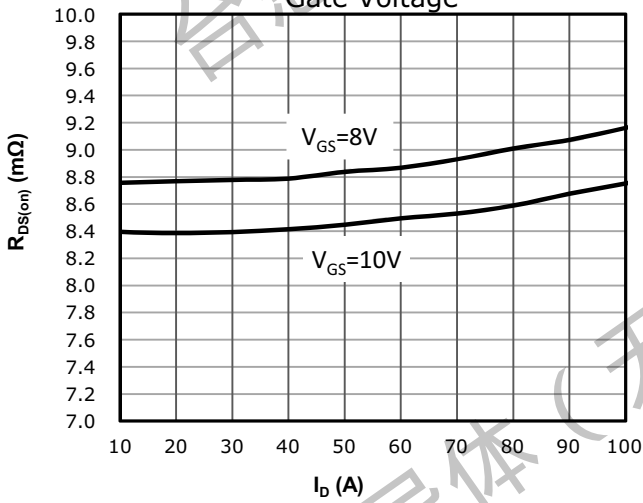


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

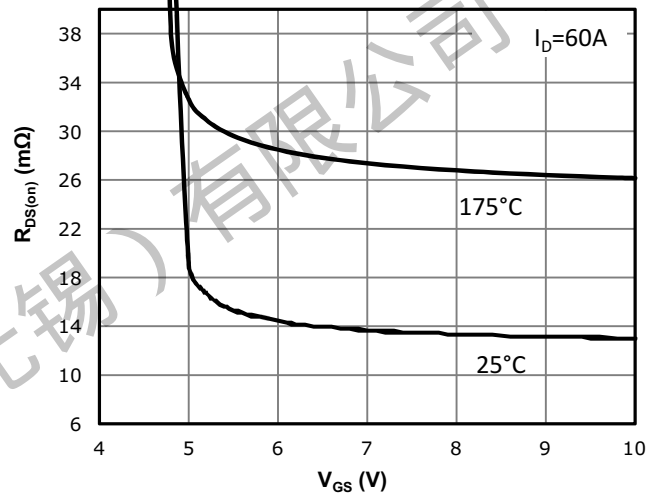


Fig 5:  $R_{DS(on)}$  vs. Temperature

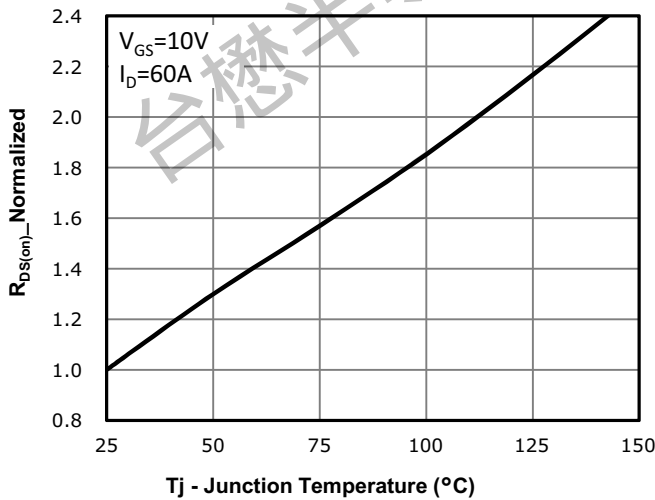
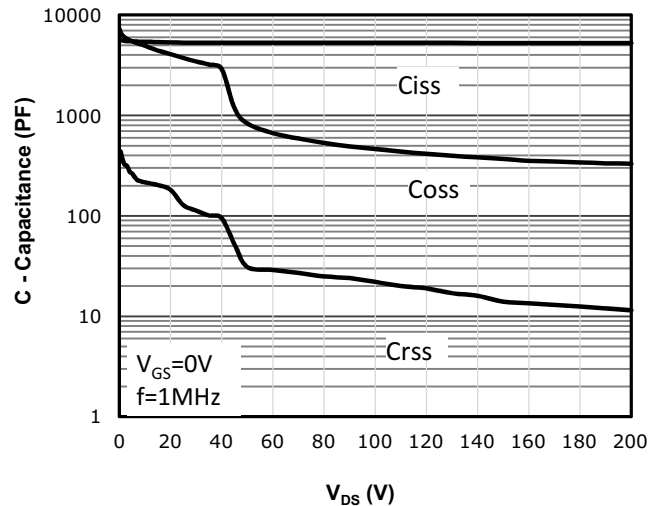


Fig 6: Capacitance Characteristics





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Fig 7: Vgs(th) vs. Temperature

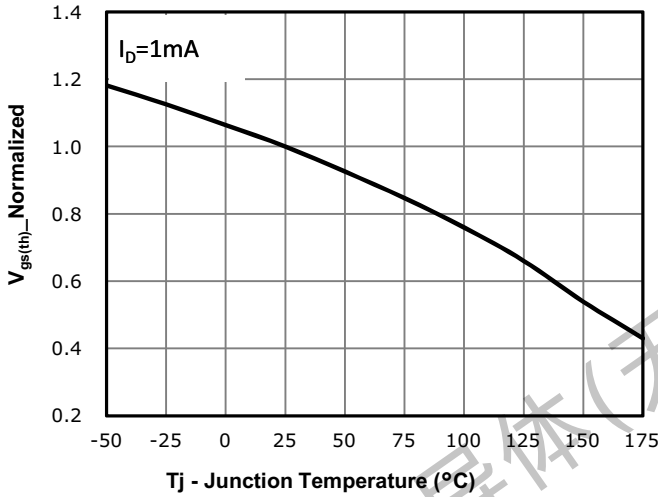


Fig 8: BVdss vs. Temperature

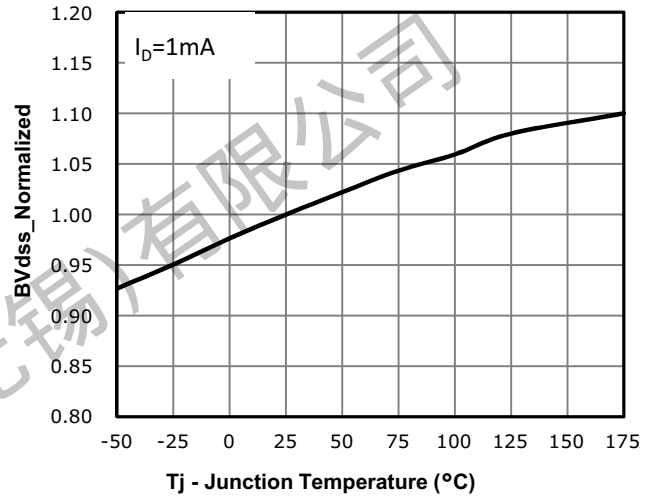


Fig 9: Gate Charge Characteristics

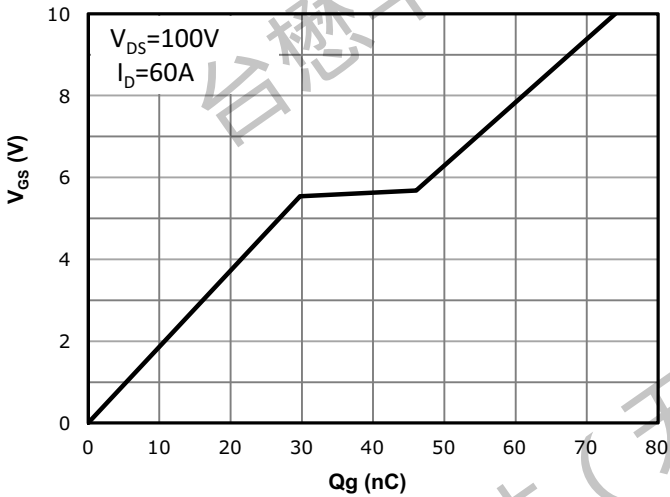


Fig 10: Body-diode Forward Characteristics

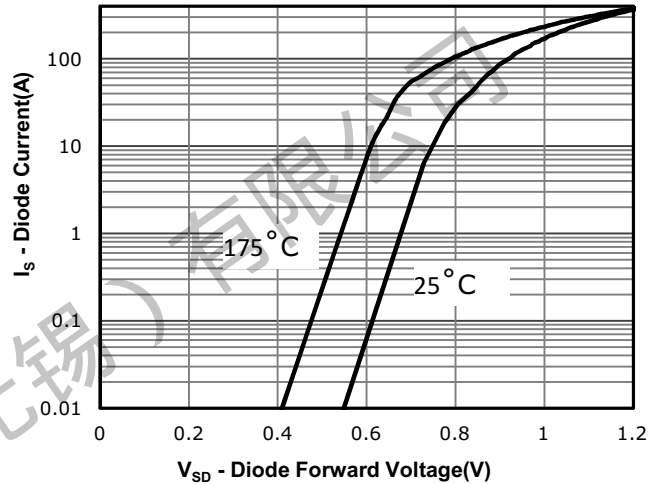


Fig 11: Power Dissipation

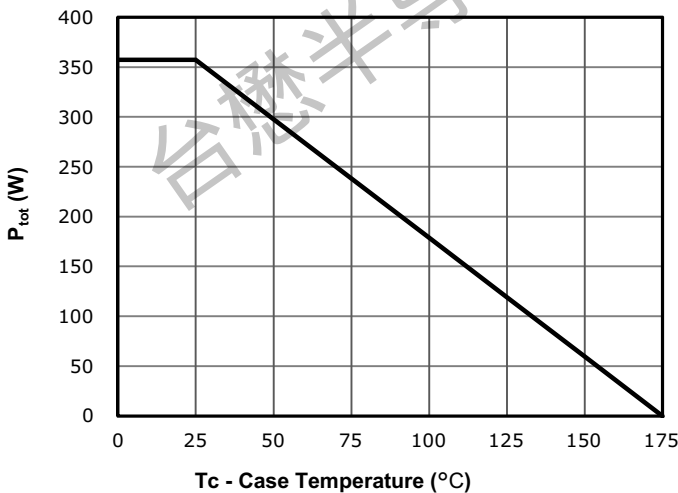
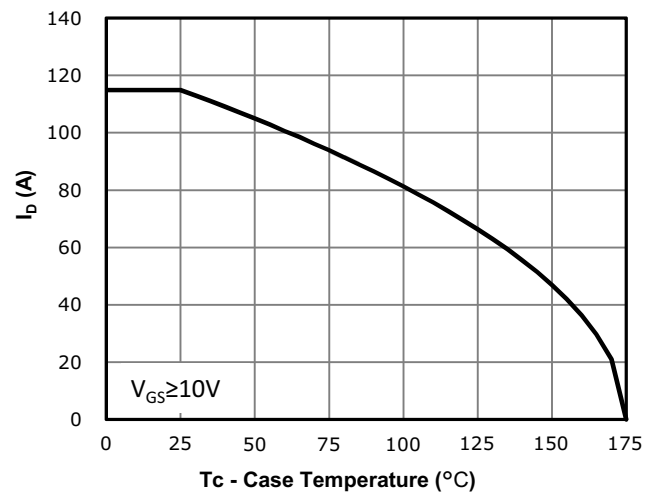


Fig 12: Drain Current Derating



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Fig 13: Safe Operating Area

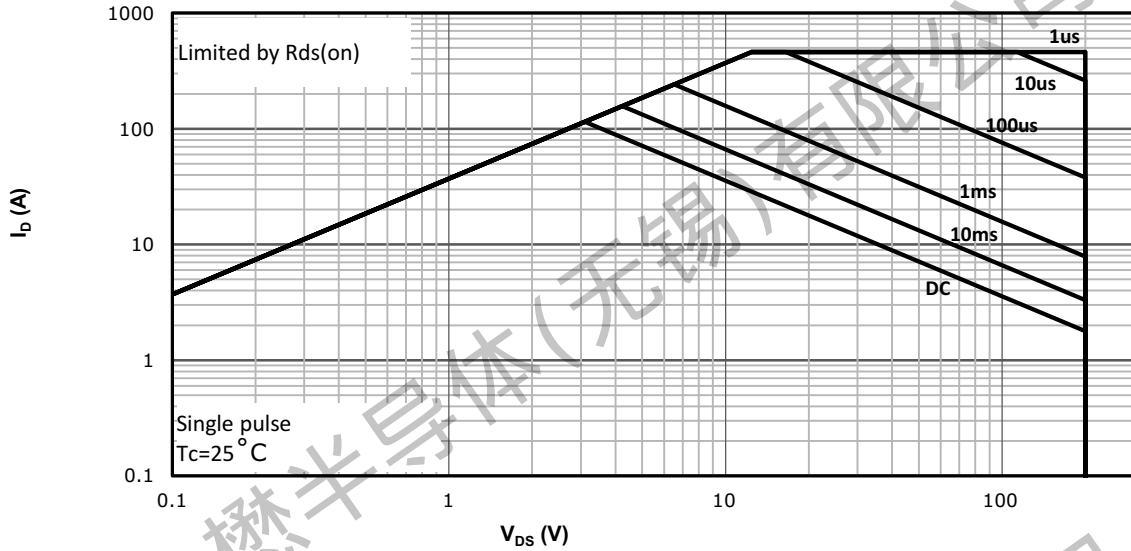
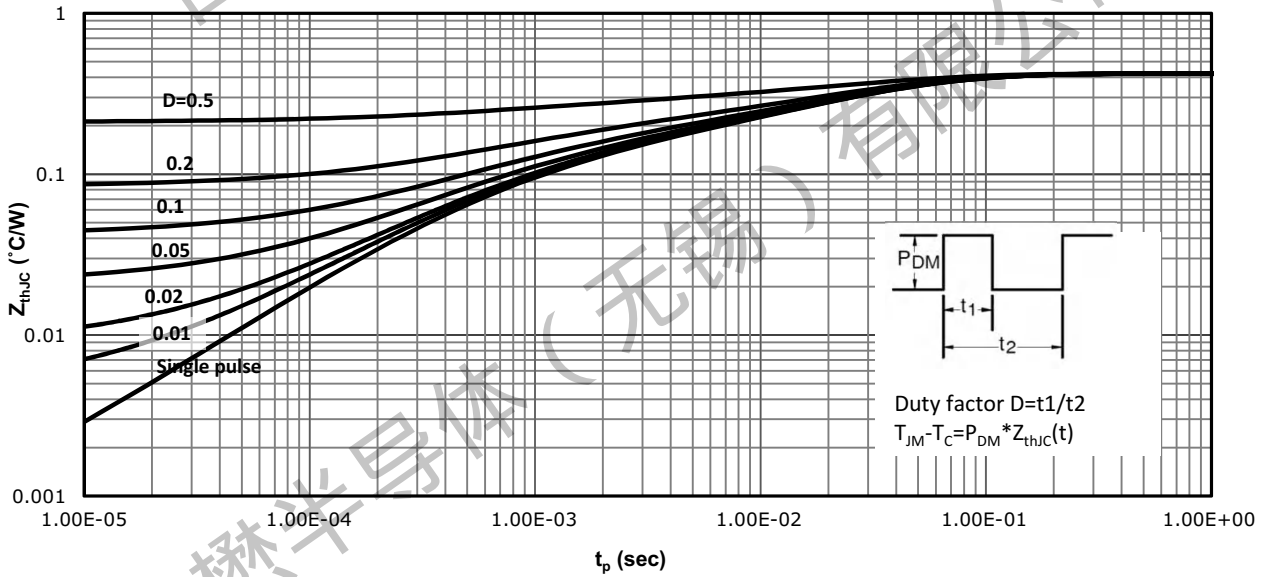


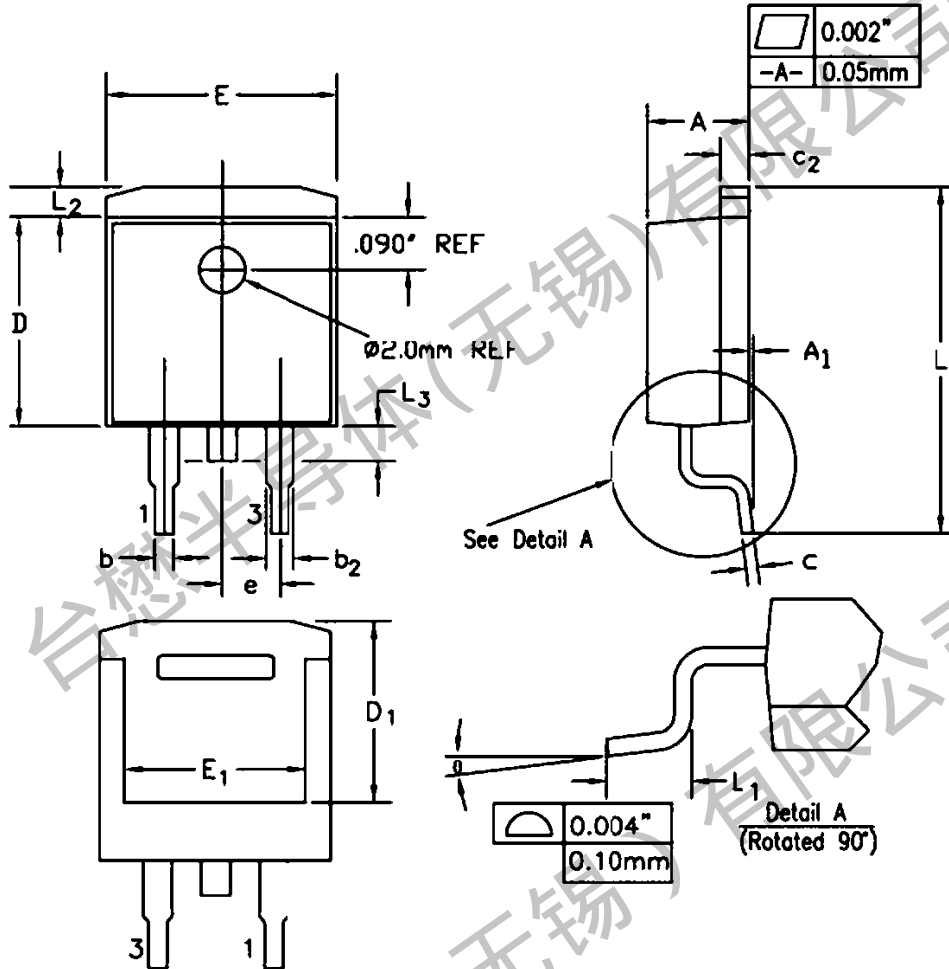
Fig 14: Max. Transient Thermal Impedance



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N-Channel Enhancement Mosfet

Package Mechanical Data: TO-263-3L



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	
A1	-	0.010	-	0.25	
b	0.028	0.037	0.71	0.94	
b2	0.045	0.055	1.15	1.40	
c	0.018	0.024	0.46	0.61	
c2	0.048	0.055	1.22	1.40	
D	0.350	0.370	8.89	9.40	
D1	0.315	0.324	8.01	8.23	
E	0.395	0.405	10.04	10.28	
E1	0.310	0.318	7.88	8.08	
e	0.100 BSC.		2.54 BSC.		
L	0.580	0.620	14.73	15.75	
L1	0.090	0.110	2.29	2.79	
L2	0.045	0.055	1.15	1.39	
L3	0.050	0.070	1.27	1.77	
θ	0°	8°	0°	8°	



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Revision history:

Date	Rev	Description	Page
2023.12.11	23.12	Original	